

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant	: Tetsuo SHIMOMURA, et al
App. No	: 10/598,717
Filed	: September 8, 2006
For	: POLISHING PAD AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD
Examiner	: Alvin J Grant
Art Unit	: 3723
Conf No.	: 9262

**AMENDMENT****Mail Stop Amendment**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated February 25, 2009, Applicants respectfully submit the following amendments and remarks in connection with the above-captioned application.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.